


MATERIAL DECLARATION SHEET



Package Type	Cx50-xxx-WH			
Product Line	Semiconductor Products			
Compliance Date	April 20, 2023			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Chip	Silicon	0.00668	Silicon	7440-21-3	100.000	6.966	6.966
2	Leadframe	Copper Alloy	0.04652	Copper	7440-50-8	97.399	47.252	48.514
				Iron	7439-89-6	2.389	1.159	
				Zinc	7440-66-6	0.127	0.062	
				Phosphorus	7723-14-0	0.076	0.037	
				Lead	7439-92-1	0.009	0.004	
		Silver Plating	0.00076	Silver	7440-22-4	100.000	0.793	0.793
3	Die Attach	Silver Epoxy	0.00174	Silver	7440-22-4	95.190	1.727	1.815
				bisphenol-F-(epichlorhydrin); epoxy resin	9003-36-5	2.756	0.050	
				1,4-bis(2,3 epoxypropoxy) butane	2425-79-8	1.061	0.019	
				Aromatic polyamine	Proprietary	0.965	0.018	
				adipic acid	124-04-9	0.028	0.001	
4	Bond wires	Gold	0.00023	Gold	7440-57-5	99.990	0.23998	0.240
				Non-Au element	Proprietary	0.010	0.00002	
5	Encapsulation	Epoxy Resin	0.03702	Silica Fused	60676-86-0	90.450	34.920	38.606
				Epoxy Resin	Proprietary	6.000	2.316	
				Phenol Resin	Proprietary	3.000	1.158	
				Carbon Black	1333-86-4	0.550	0.212	
6	Terminal Finish	Tin	0.00294	Tin	7440-31-5	100.000	3.066	3.066
			Total Weight				0.09589	

This Document was updated on: April 20, 2023

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.